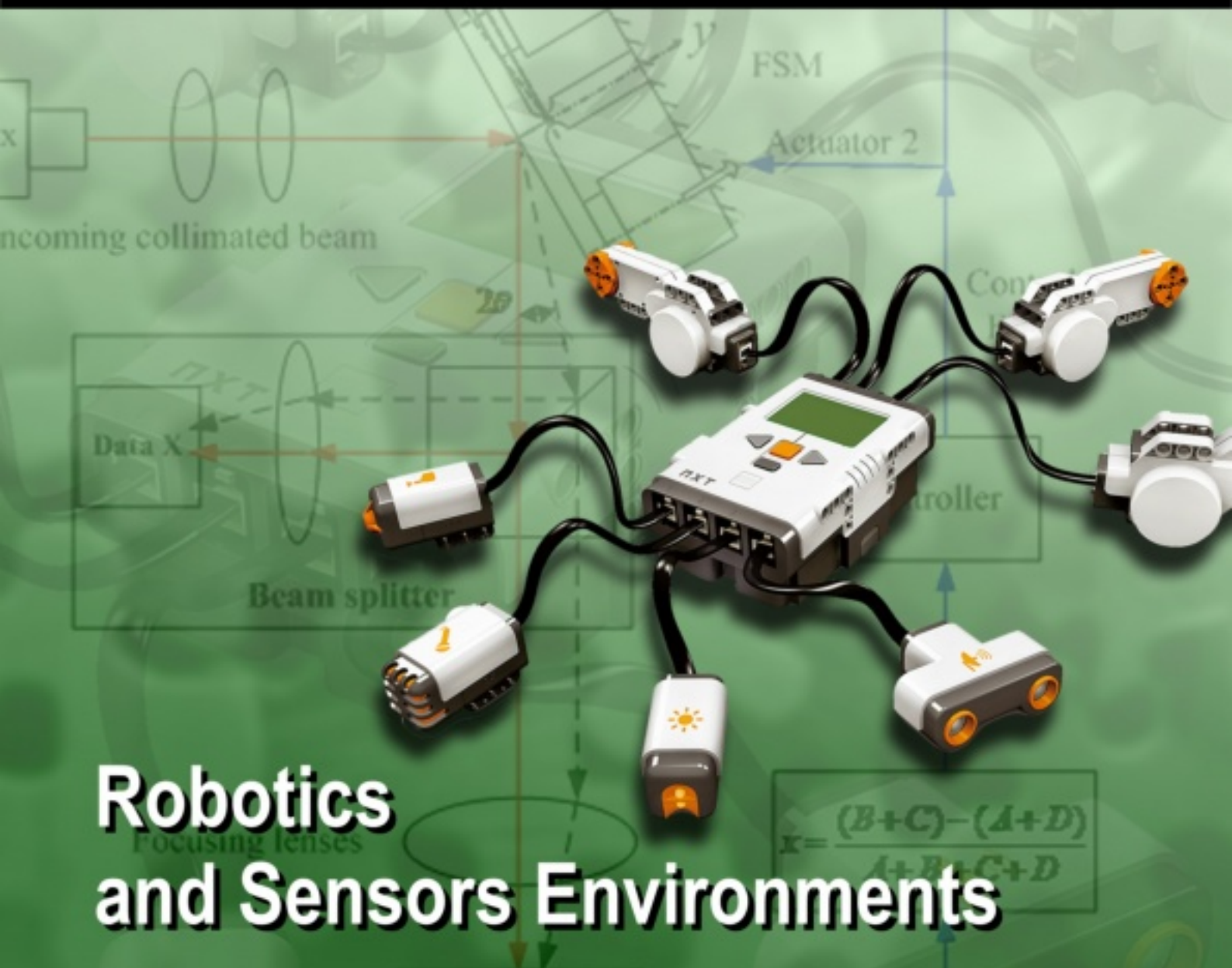


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# SENSORS & TRANSDUCERS

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# Contents

Volume 5  
Special Issue  
March 2009

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ISSN 1726-5479

## Research Articles

### Foreword

*Pierre Payeur and Emil Petriu* ..... 1

### An Omnidirectional Stereoscopic System for Mobile Robot Navigation

*Rémi Bouteau, Xavier Savatier, Jean-Yves Ertaud, Bélahcène Mazari* ..... 3

### Movement in Collaborative Robotic Environments Based on the Fish Shoal Emergent Patterns

*Razvan Cioarga, Mihai V. Micea, Vladimir Cretu, Emil M. Petriu*..... 18

### A Multiscale Calibration of a Photon Videomicroscope for Visual Servo Control: Application to MEMS Micromanipulation and Microassembly

*Brahim Tamadazte, Sounkalo Dembélé and Nadine Piat*..... 37

### A Study on Dynamic Stiffening of a Rotating Beam with a Tip Mass

*Shengjian Bai, Pinhas Ben-Tzvi, Qingkun Zhou, Xinsheng Huang*..... 53

### Towards a Model and Specification for Visual Programming of Massively Distributed Embedded Systems

*Meng Wang, Varun Subramanian, Alex Doboli, Daniel Curiac, Dan Pescaru and Codruta Istin* ..... 69

### Feature Space Dimensionality Reduction for Real-Time Vision-Based Food Inspection

*Mai Moussa CHETIMA and Pierre PAYEUR* ..... 86

### Design and Analysis of a Fast Steering Mirror for Precision Laser Beams Steering

*Qingkun Zhou, Pinhas Ben-Tzvi and Dapeng Fan*..... 104

### Neural Gas and Growing Neural Gas Networks for Selective 3D Sensing: a Comparative Study

*Ana-Maria Cretu, Pierre Payeur and Emil M. Petriu*..... 119

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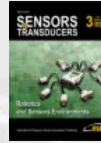
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Vol. 5, March 2009**

[Table of Contents](#)

Journal's CD 2008:



**Selected Papers from the 6<sup>th</sup> IEEE International Workshop on Robotic and Sensors Environments (ROSE 2008)**

17-18 October 2008, Ottawa, Ontario, Canada  
Edited by **Dr. Pierre Payeur** and **Dr. Emil Petriu**

**Foreword**

**Pierre Payeur, Emil Petriu, pp.1-2**  
[Full Text Download]

**An Omnidirectional Stereoscopic System for Mobile Robot Navigation**

*Rémi Boutteau, Xavier Savatier, Jean-Yves Ertaud, Bélahcène Mazari, pp.3-17*  
[Abstract and Full Text Article Download]

**Movement in Collaborative Robotic Environments Based on the Fish Shoal Emergent Patterns**

*Razvan Cioarga, Mihai V. Micea, Vladimir Cretu, Emil M. Petriu, pp.18-36*  
[Abstract and Full Text Article Download]

**A Multiscale Calibration of a Photon Videomicroscope for Visual Servo Control: Application to MEMS Micromanipulation and Microassembly**

*Brahim Tamadazte, Soukalo Dembélé and Nadine Piat, pp. 37-52*

**A Study on Dynamic Stiffening of a Rotating Beam with a Tip Mass**

*Shengjian Bai, Pinhas Ben-Tzvi, Qingkun Zhou, Xinsheng Huang, pp. 53-68*

**Towards a Model and Specification for Visual Programming of Massively Distributed Embedded Systems**

*Meng Wang, Varun Subramanian, Alex Doboli, Daniel Curiac, Dan Pescaru and Codruta Istin, pp. 69-85*

**Feature Space Dimensionality Reduction for Real-Time Vision-Based Food Inspection**

*Mai Moussa Chetima and Pierre Payeur, pp.86-103*

**Design and Analysis of a Fast Steering Mirror for Precision Laser Beams Steering**

*Qingkun Zhou, Pinhas Ben-Tzvi and Dapeng Fan, pp.104-118*

**Neural Gas and Growing Neural Gas Networks for Selective 3D Sensing: a Comparative Study**

*Ana-Maria Cretu, Pierre Payeur and Emil M. Petriu, pp.119-134*

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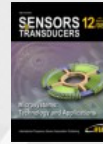
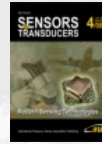
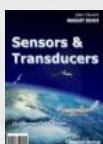
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